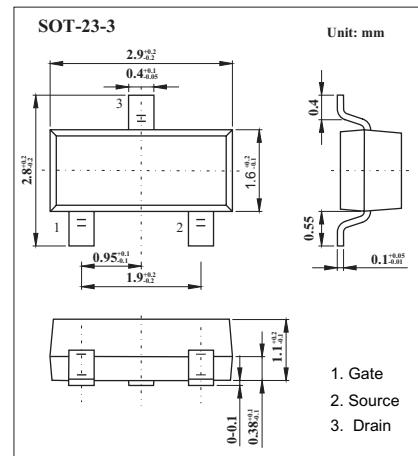
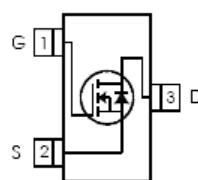


KRLML2502

■ Features

- Ultra Low On-Resistance
- N-Channel MOSFET
- Low Profile (<1.1mm)
- Available in Tape and Reel
- Fast Switching



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit
Drain- Source Voltage	V _{DS}	20	V
Gate-to-source voltage	V _{GS}	±12	V
Continuous drain current,V _{GS} @4.5V	I _D	4.2	A
Pulsed drain current	I _{DM}	33	A
Power dissipation	P _D	1.25	W
Linear derating factor		0.01	W°C
Junction-to-ambient *	R _{θJA}	75	°C/W
Junction and storage temperature range	T _{J,TSTG}	-55 to +150	°C

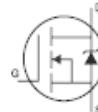
* Surface mounted on FR-4 board,t≤5 sec.

KRLML2502

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Drain-source Breakdown voltage	V(BR)DSS	ID= 250 µA, VGS = 0V	20			V
Static drain-source on-state resistance *	RDS(on)	ID= 4.2A, VGS = 4.5V		0.035	0.045	Ω
		ID=3.6A, VGS = 2.5V		0.050	0.080	
Gate threshold voltage	VGS(th)	VDS = VGS, ID= 250 µA	0.6		1.2	V
Forward Transconductance	gfs	VDS = 10 V, ID = 4.0 A	5.8			S
Gate-source leakage current	Idss	VDS = 16 V, VGS = 0V			1.0	µ A
		VDS = 16 V, VGS = 0V, TJ=70°C			25	
Gate-source forward leadage	Igss	VGS = -12V			-100	nA
Gate-source reverse leadage		VGS = 12V			100	
Input capacitance	Ciss	VDS = 15 V, VGS = 0 V, f= 1MHz		740		pF
Output capacitance	Coss			90		
Reverse transfer capacitance	Crss			66		
Total Gate Charge	Qg	VDS = 5.0V ,VGS = 10 V , ID= 4.0 A		8.0	12	nC
Gate-Source Charge	Qgs			1.8	2.7	
Gate-Drain Charge	Qgd			1.7	2.6	
Turn-on delay time	td(on)	ID= 1 A, VDD= 10V, RD= 10 Ω RG= 6. Ω		7.5		ns
Rise time	tr			10		
Turn-off delay time	td(off)			54		
Fall time	tr			26		
Reverse recovery time *	trr	TJ=25°C, IF = 1.3 A, di / dt = 100 A/ µ s		16	24	ns
Reverse recovery charge *	Qrr			8.6	13	nC
Continuous source current	Is	MOSFET symbol I showing the integral reverse p-n junction diode			1.3	A
Pulsed source current	ISM				33	
Diode forward voltage *	VSD	TJ=25°C, VGS = 0 V, Is = 1.3 A			1.2	V

* Pulse width ≤ 300 µ s, Duty cycle ≤ 2%



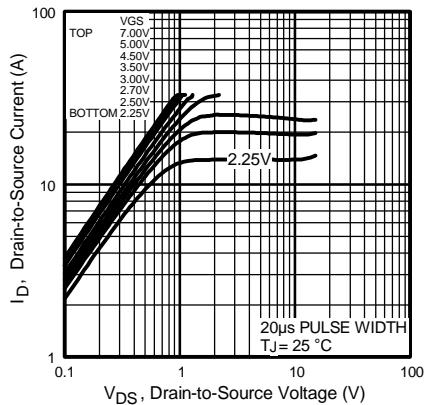


Fig 1. Typical Output Characteristics

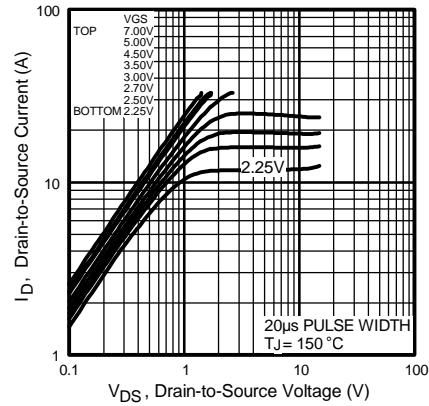


Fig 2. Typical Output Characteristics

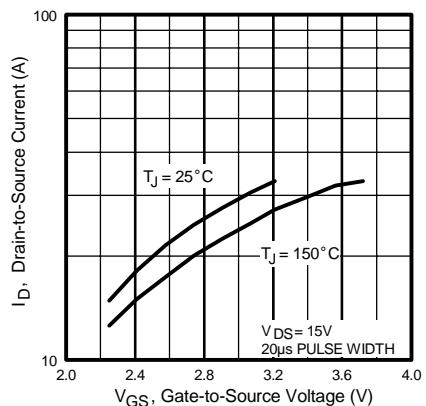


Fig 3. Typical Transfer Characteristics

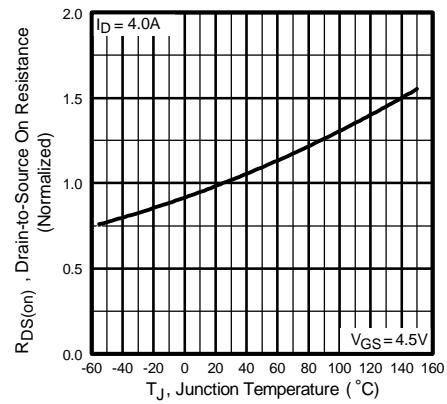


Fig 4. Normalized On-Resistance Vs. Temperature

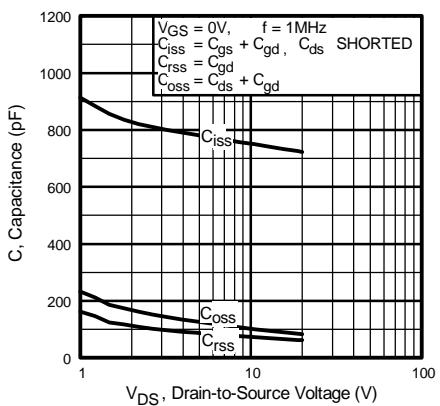


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

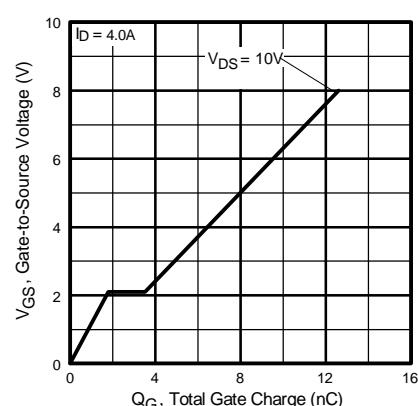


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

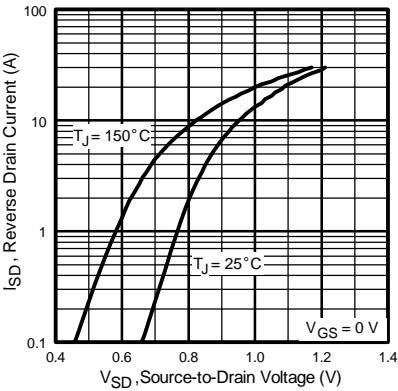


Fig 7. Typical Source-Drain Diode Forward Voltage

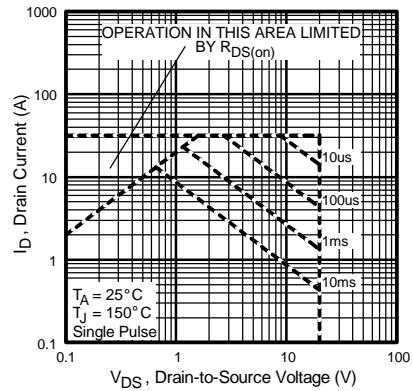


Fig 8. Maximum Drain Current Vs. Case Temperature₃

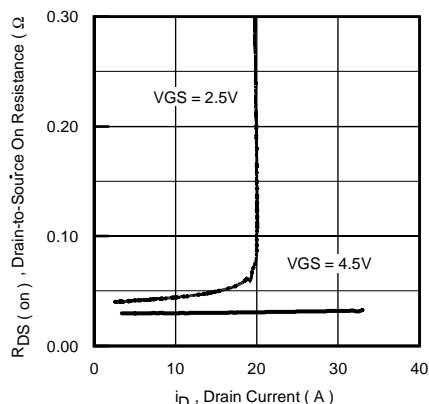


Fig 9. On-Resistance Vs. Drain Current

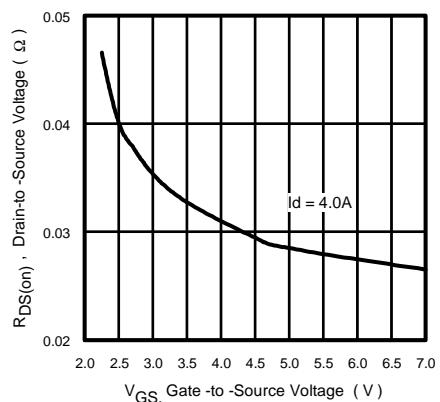


Fig 10. On-Resistance Vs. Gate Voltage

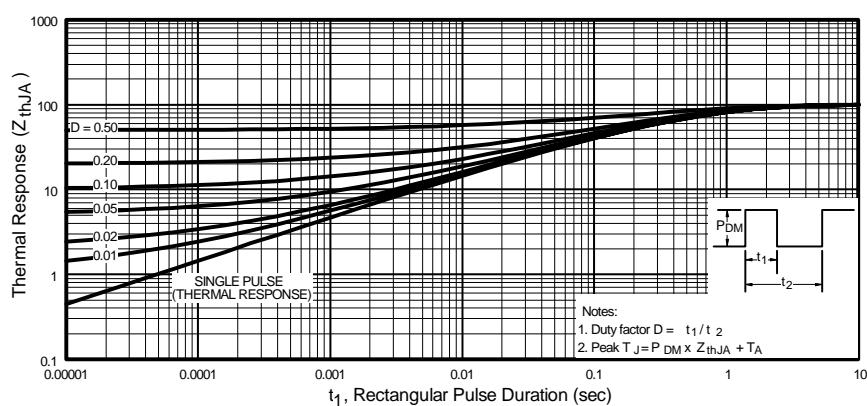


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient